

Features

- 3.5mm X 3.5mm X 1.15mm SMD LED
- Zener diode provided for ESD Protection
- IR-reflow compatible
- Ideal for accent lighting
- Standard Package: 2,000pcs / Reel
- MSL (Moisture Sensitivity Level): 2a
- RoHS compliant

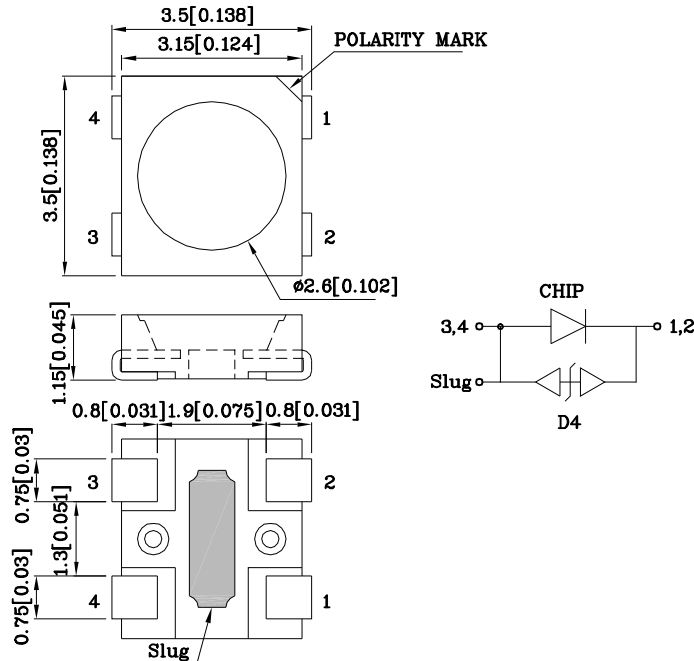
Applications

- Signal and symbol luminaire for orientation.
- Marker lights (e.g. steps, exit ways, etc).
- Decorative and entertainment lighting.
- Commercial and residential lighting.
- Automotive interior lighting.



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Package Schematics



Notes:

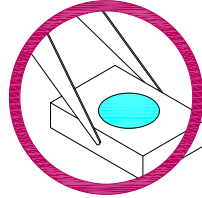
1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25 (0.01")$ unless otherwise noted.
3. Specifications are subject to change without notice.

Handling Precautions

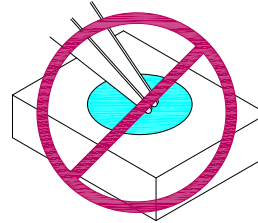
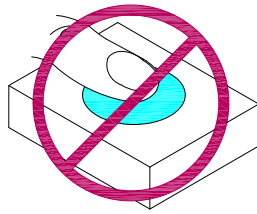
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

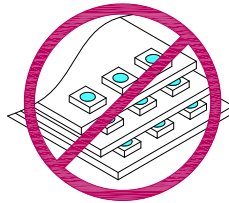
1. Handle the component along the side surfaces by using forceps or appropriate tools.



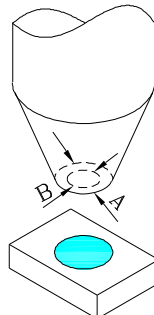
2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (IF=150mA) cd		Luminous Flux CIE127-2007* (IF=150mA)* lm		Viewing Angle 2 θ 1/2 [1]
				min.	typ.	min.	typ.	
XZCB25X92S-4	Blue	InGaN	Water Clear	0.7*	1.295*	2.4*	3.3*	120°

Notes:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity / luminous flux: +/-15%.

3. LEDs are binned according to their luminous flux.

* Luminous intensity / luminous flux value is in accordance with CIE127-2007 standards.

Absolute Maximum Ratings at TA=25°C

Parameter	Symbol	Value	Unit
Power Dissipation	PD	600	mW
Junction Temperature [1]	TJ	110	°C
Operating Temperature	Top	-40 To +85	°C
Storage Temperature	Tstg	-40 To +85	°C
DC Forward Current[1]	IF	150	mA
Peak Forward Current [2]	IFM	300	mA
Reverse Voltage	VR	5	V
Thermal Resistance [1] (Junction/ambient)	Rth j-a	180	°C/W
Thermal Resistance [1] (Junction/solder point)	Rth j-S	85	°C/W
Electrostatic Discharge Threshold (HBM)		8000	V

Notes:

1.Results from mounting on PC board FR4(pad size≥70mm²), mounted on pc board-metal core PCB is recommend for lowest thermal Resistance.

2.1/10 Duty Cycle, 0.1ms Pulse Width.

Electrical / Optical Characteristics at TA=25°C

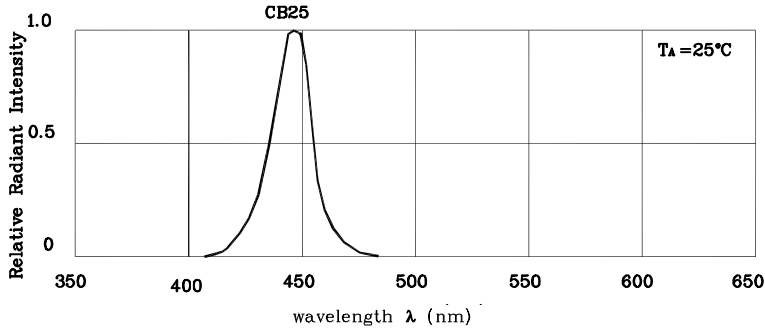
Parameter	Symbol	Value	Unit
Forward Voltage IF = 150mA [Min.]	VF [2]	2.7	V
Forward Voltage IF = 150mA [Typ.]		3.5	
Forward Voltage IF = 150mA [Max.]		4.0	
Allowable Reverse Current [Max.]	IR	85	mA
Wavelength at peak emission IF=150mA CIE127-2007* [Typ.]	λ peak	445*	nm
Dominant Wavelength IF=150mA CIE127-2007* [Typ.]	λ dom [1]	450*	nm
Spectral bandwidth at 50% Φ REL MAX IF = 150mA [Typ.]	Δλ	20	nm
Temperature coefficient of λ peak IF = 150mA, - 10°C ≤ T ≤ 100°C [Typ.]	TC λ peak	0.12	nm/°C
Temperature coefficient of λ dom IF = 150mA, - 10°C ≤ T ≤ 100°C [Typ.]	TC λ dom	0.10	nm/°C
Temperature coefficient of VF IF = 150mA, - 10°C ≤ T ≤ 100°C [Typ.]	TCv	-2.3	mV/°C

Notes:

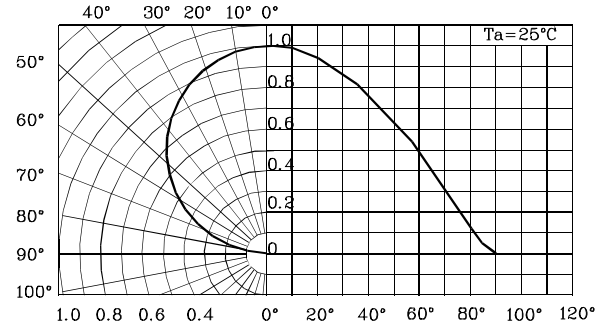
1.The dominant Wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd : ±1nm.)

2. Forward Voltage: +/-0.1V.

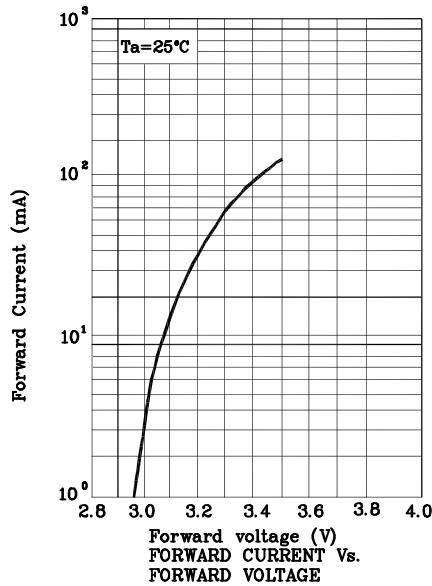
*Wavelength value is in accordance with CIE127-2007 standards.



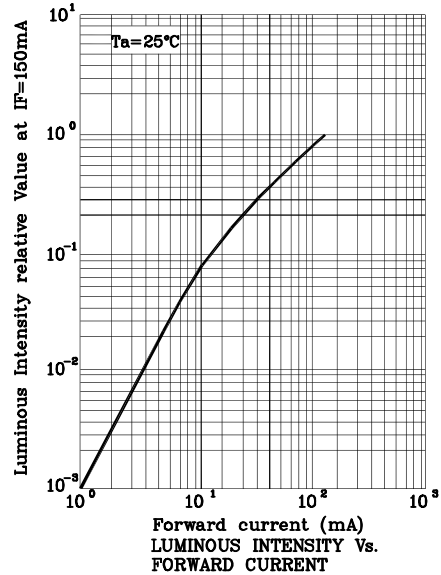
RELATIVE INTENSITY Vs. CIE WAVELENGTH



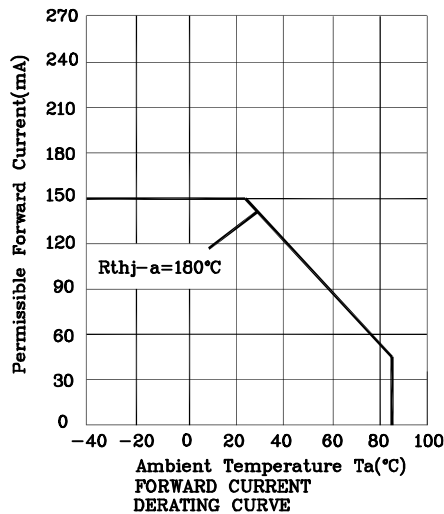
SPATIAL DISTRIBUTION



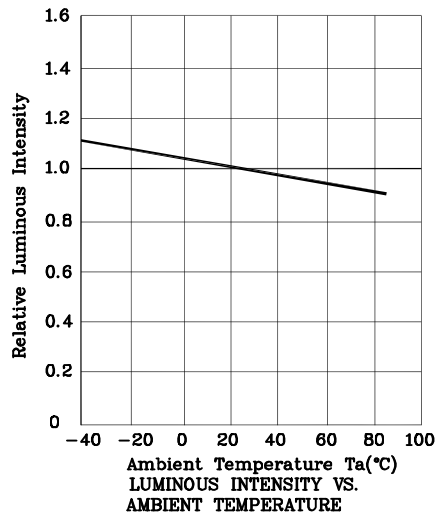
FORWARD CURRENT Vs.
FORWARD VOLTAGE



LUMINOUS INTENSITY Vs.
FORWARD CURRENT



FORWARD CURRENT
DERATING CURVE

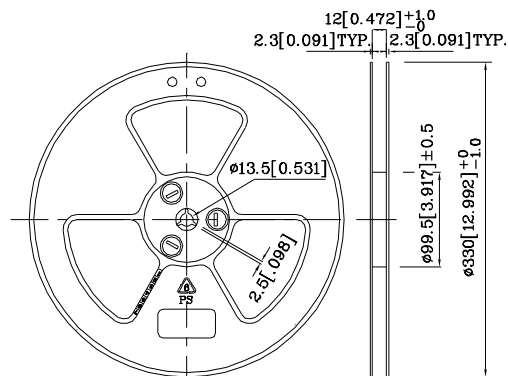


LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

❖ The device has a single mounting surface. The device must be mounted according to the specifications.

Figure 1 is a graph showing the temperature profile of a polymer melt during the extrusion of a monolayer film. The y-axis represents Temperature (°C) from 0 to 300, and the x-axis represents Time (sec) from 0 to 300. The profile starts at 25°C, rises at 4°C/s to 150°C (60~120s), then at 4°C/s to 230°C (30~50s), peaks at 260°C (10 s max), and finally cools at 4°C/s.

-



Technical drawing of the test specimen showing top, side, and detail views with dimensions and labels.

Top View Dimensions:

- Overall width: 12 ± 0.3
- Overall length: 8 ± 0.1
- Distance between top holes: 4 ± 0.1
- Distance between bottom holes: 2 ± 0.1
- Hole diameter: $\phi 1.50 \pm 0.1$
- Bottom hole spacing: 1 and 2 (left), 4 and 3 (right)

Side View Dimensions:

- Top thickness: 1.75 ± 0.1
- Bottom thickness: 5.5 ± 0.05

Detail View Dimensions:

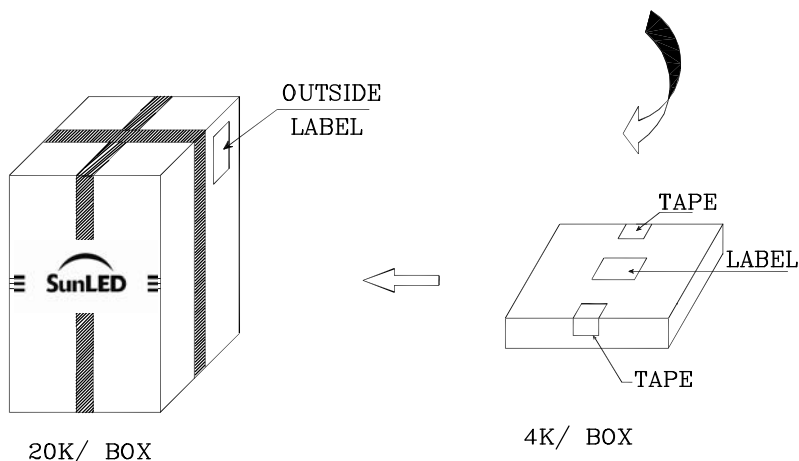
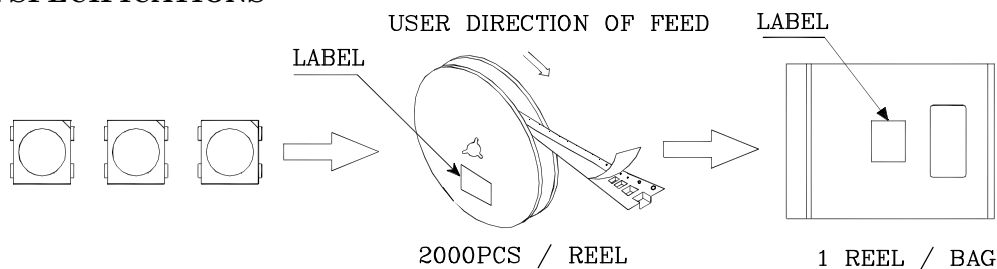
- Top thickness: 0.25 ± 0.1
- Bottom thickness: 1.42 ± 0.1


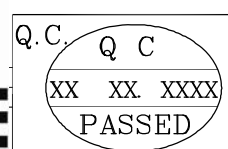

Labels and Features:

- TAPE** with an arrow pointing right.
- 1,2** and **3,4** labels on the detail view.
- D4** label on the detail view.
- Slug** label on the detail view.



PACKING & LABEL SPECIFICATIONS



 	
P/NO : XZxxx92x	
QTY : 2000 pcs	CODE: XXX
S/N : XX	
LOT NO :  XXXXXXXXXXXXXXXXXXXXXXXX	
RoHS Compliant	

TERMS OF USE

1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
2. Contents within this document are subject to improvement and enhancement changes without notice.
3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
5. The contents within this document may not be altered without prior consent by SunLED.
6. Additional technical notes are available at <http://www.SunLEDusa.com/TechnicalNotes.asp>